



SCIENTECH

(3583)

2018/5/23

Safe Harbor Statement



- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.



Scientech Corp (3583: TT)

Company Establishment	1979/10/17	
IPO	2013/3/12	
Capital	NT\$ 811 Million	
Chairman	H.L. Hsieh	
President	M.T. Hus	
Products	Equipment Manufacturing • Wa Trading(Agent/Distributor)	afer Reclaim



Business Overvies

Products

Future

Prospect

Business Overview

Income Statement



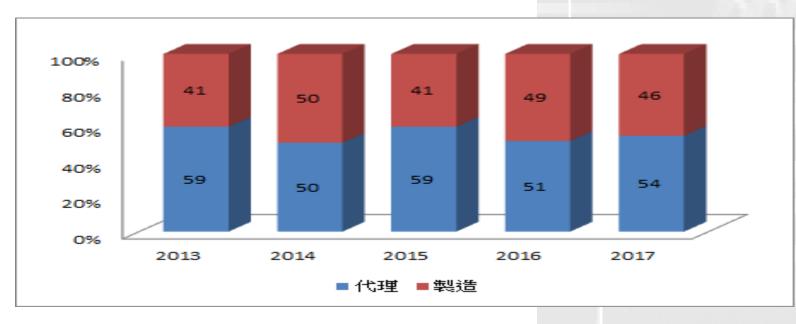
Units:NT \$ M	2013	2014	2015	2016	2017	1Q18
Revenues	3,068	2,717	2,942	3,495	3,539	694
Gross Profit	983	970	903	1,178	1,251	239
Operating Expenses	629	673	779	835	829	199
Operating Income	354	297	124	343	423	40
Other Income and Expenses	(26)	20	(6)	21	(8)	(22)
Income Before Tax	328	317	119	363	415	18
Net Income	249	246	86	292	328	16
EPS	3.11	3.04	1.06	3.60	4.05	0.19
Gross Margin	32.04%	35.71%	30.69%	33.71%	35.36%	34.39%
Operating Margin	11.53%	10.93%	4.23%	9.80%	11.95%	5.71%
Income Before Tax margin	10.69%	11.68%	4.03%	10.40%	11.72%	2.57%

Business Overview





Units : %	2013	2014	2015	2016	2017	Gross Margin
Trading	59	50	59	51	54	Below Average
Manufacturing	41	50	41	49	46	Above Average



Business Overview





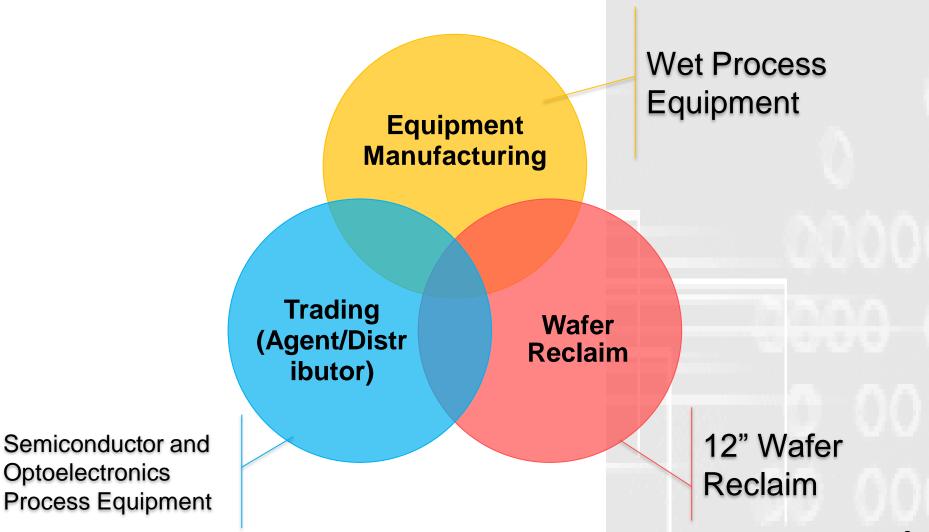
Units:NT\$M	2013	2014	2015	2016	2017
R&D Expenses	131	160	196	226	228
Expenses as % of Revenue	4.27%	5.89%	6.66%	6.48%	6.44%



7

Products





Products

Equipment Manufacturing



Wet process equipment

- Single wafer/ Batch type
 - 8"/12' Advanced packaging

 (Fan-out < Solder Bump <
 Copper Pillow < Bumping
 Gold Bump < RDL < TSV
 ...ect)

 - HB LED fully-automatic process
 - MEMS
 - ♦ III-V



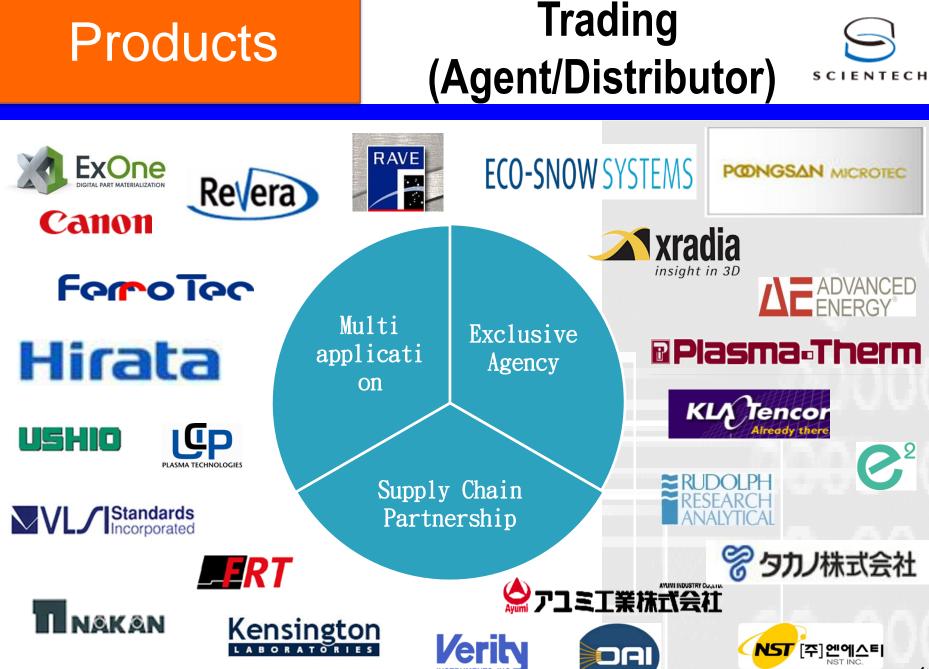
Products

Line

Si Wafer Reclaim



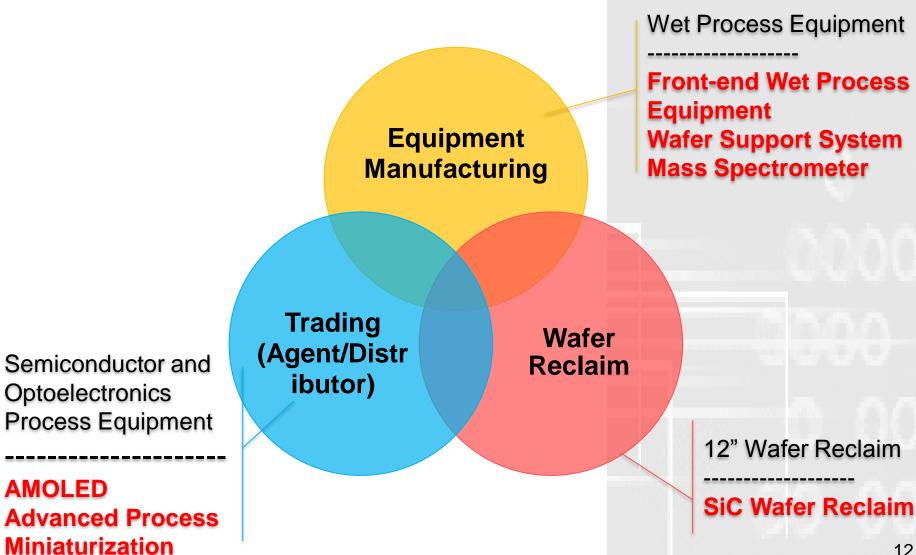
Advanced clean technology Complete particle inspection 20nm/ 16nm Particle (SP1-DLS & SP2) Low trace metal (<5E9) 12" Wafer Reclaim Etching Cleaning Capacity: 120K / month Separated Cu & Non Cu Full Process **Optimization** <mark>Grindin</mark>sj Rolishing **Complete polishing process Super flatness** Single side polish (GBIR<0.5µm) **Double, side polish Final Haze polish** 10



Future Prospect

Product-based Extension











Thank You!